



## Description

The IRLR8721TRPBF-1 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.



## General Features

$V_{DS} = 30V$   $I_D = 80A$

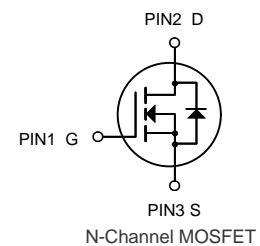
$R_{DS(ON)} < 6.8m\Omega @ V_{GS} = 10V$

## Application

Battery protection

Load switch

Uninterruptible power supply



## Ordering Information

Product ID	Pack	Brand	Qty(PCS)
IRLR8721TRPBF-1	TO-252-2L	HXY MOSFET	2500

## Absolute Maximum Ratings ( $T_c = 25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	30	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current – Continuous ( $T_c = 25^\circ C$ )	80	A
	Drain Current – Continuous ( $T_c = 100^\circ C$ )	51	A
$I_{DM}$	Drain Current – Pulsed	320	A
EAS	Single Pulse Avalanche Energy	88	mJ
IAS	Single Pulse Avalanche Current	42	A
$P_D$	Power Dissipation ( $T_c = 25^\circ C$ )	54	W
	Power Dissipation – Derate above $25^\circ C$	0.43	W/ $^\circ C$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$
$R_{\theta JA}$	Thermal Resistance Junction to ambient	62	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction to Case	2.3	$^\circ C/W$



**Electrical Characteristics (T<sub>J</sub>=25°C, unless otherwise noted)**

Symbol	Parameter	Test Conditions	Typical Value	Min.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	30	---	---	V
ΔBVDSS/ΔT <sub>J</sub>	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C, I <sub>D</sub> =1mA	---	0.04	---	V/°C
IDSS	Drain-Source Leakage Current	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =24V, V <sub>GS</sub> =0V, T <sub>J</sub> =125°C	---	---	10	uA
IGSS	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±100	nA
RDS(on)	Static Drain-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =20A	---	5	6.8	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =10A	---	6.5	9	mΩ
VGS(th)	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1	1.6	2.5	V
ΔVGS(th)	V <sub>GS(th)</sub> Temperature Coefficient		---	-4	---	mV/°C
gfs	Forward Transconductance	V <sub>DS</sub> =10V, I <sub>D</sub> =10A	---	18	---	S
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =15V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A	---	11.1	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	1.85	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	6.8	---	
Td(on)	Turn-On Delay Time	V <sub>DD</sub> =15V, V <sub>GS</sub> =10V, R <sub>G</sub> =3.3Ω, I <sub>D</sub> =15A	---	7.5	---	ns
T <sub>r</sub>	Rise Time		---	14.5	---	
Td(off)	Turn-Off Delay Time		---	35.2	---	
T <sub>f</sub>	Fall Time		---	9.6	---	
Ciss	Input Capacitance	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, F=1MHz	---	1160	---	pF
Coss	Output Capacitance		---	200	---	
Crss	Reverse Transfer Capacitance		---	180	---	
R <sub>g</sub>	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, F=1MHz	---	2.5	---	Ω
EAS	Single Pulse Avalanche Energy	V <sub>DD</sub> =25V, L=0.1mH, I <sub>AS</sub> =20A	20	---	---	mJ
IS	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	80	A
ISM	Pulsed Source Current		---	---	320	A
VSD	Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =1A, T <sub>J</sub> =25°C	---	---	1	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> =0V, I <sub>S</sub> =1A, di/dt=100A/μs, T <sub>J</sub> =25°C	---	---	---	ns
Q <sub>rr</sub>	Reverse Recovery Charge		---	---	---	nC



## Typical Characteristics

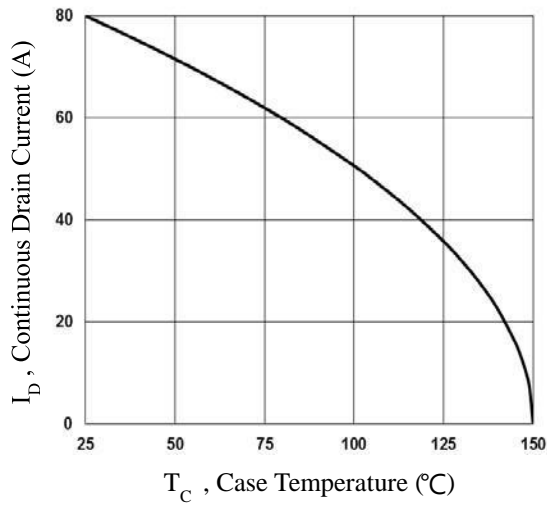


Fig.1 Continuous Drain Current vs.  $T_C$

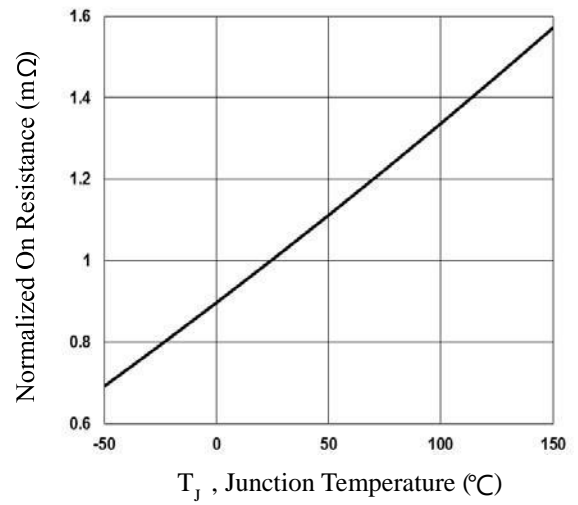


Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_J$

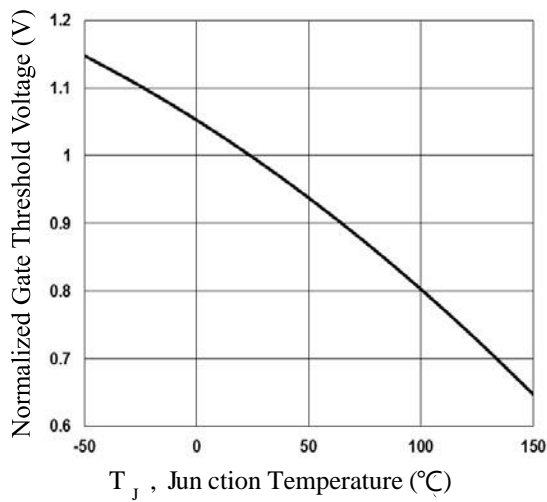


Fig.3 Normalized  $V_{th}$  vs.  $T_J$

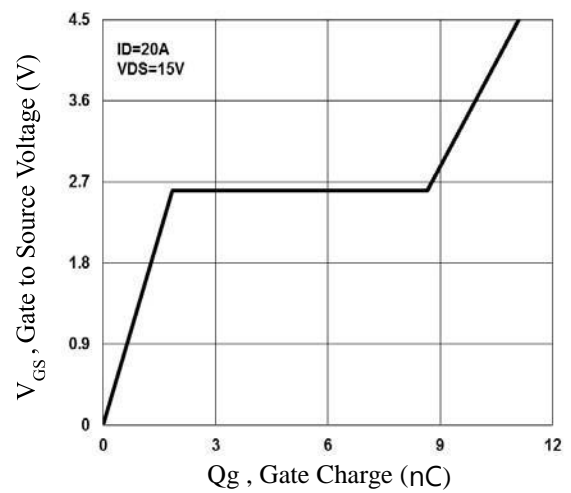


Fig.4 Gate Charge Waveform

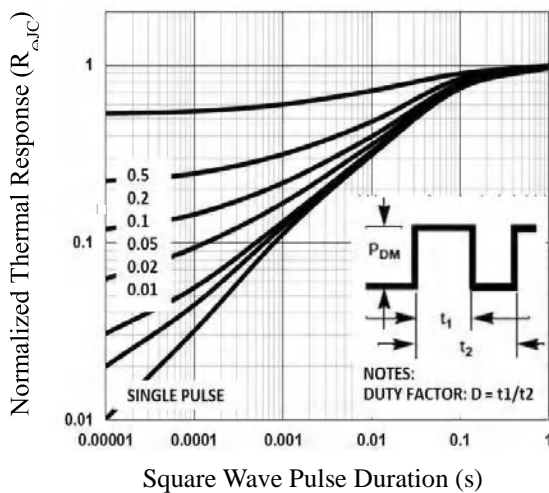


Fig.5 Normalized Transient Impedance

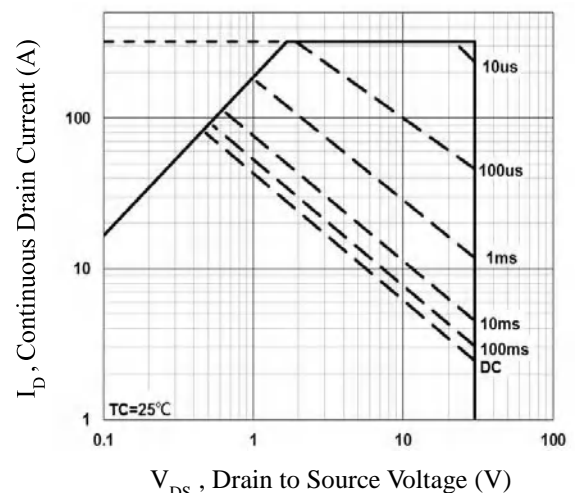


Fig.6 Maximum Safe Operation Area

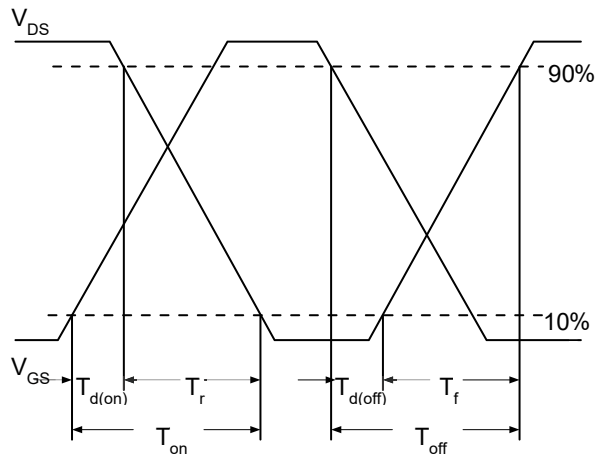


Fig. 7 Switching Time Waveform

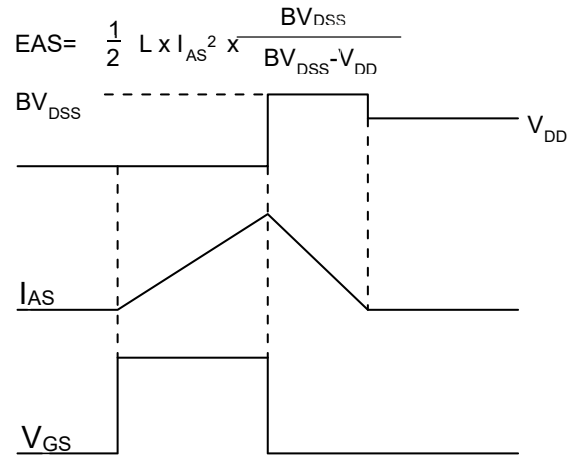
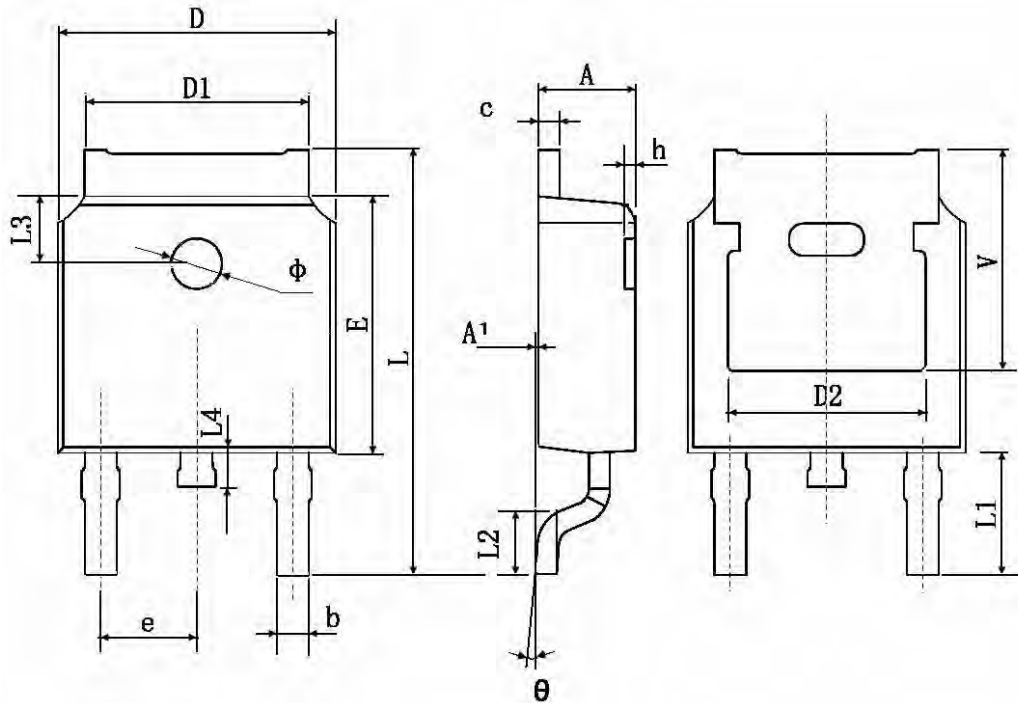


Fig. 8 EAS Waveform

## TO-252-2L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	0.483 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	



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